

## **CMP Oxide Slurry**



## ACESOL<sup>®</sup> Series

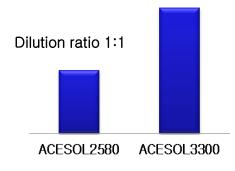
- 1280 Undiluted
- 2580 1:1 diluted
- 3300 1:2 diluted

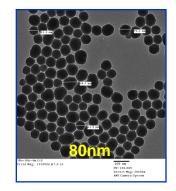


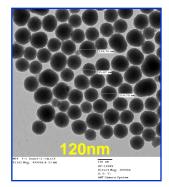
- Colloidal silica for chemical mechanical planarization(CMP)
- Non-agglomerating slurries with special particle distributions
- Various range of particle sizes offered to meet R/R
- ACESOL® Series diluted as a 2x, 3x concentrated CMP Oxide slurry to reduce handling and shipping costs
- Shelf life is more than 12months
- •Abrasive silica for metal slurry











## **Features & Benefits**

- ✓ Long shelf life and high removal rate Control the particle size for high R/R
- ✓ Lower cost of ownership Improve dilution rate for cost down
- Less risk of scratch and tool down time Colloidal silica showing soft particle good for scratch